ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH ACTIVE SURFACE HEAT REMOVAL AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: providing an interconnect structure having a structure bottom side, a structure top side, and a cavity, the structure bottom side electrically connected to the structure top side; mounting an integrated circuit entirely within the cavity, the integrated circuit having an active side coplanar with the structure top side; forming an encapsulation partially covering the interconnect structure and the integrated circuit, the encapsulation having an encapsulation top side coplanar with the structure top side and the active side; forming a top re-passivation layer over the structure top side and the encapsulation; and mounting a heat sink over the top re-passivation layer for removing heat from the active side.
(Fig 1)